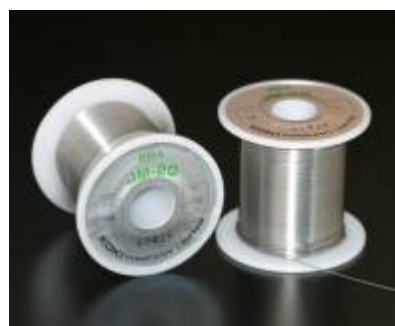


No-clean Flux Cored Wire Solder

JM - 20

■ Feature

- 1) Halide free, extremely high reliability.
- 2) Excellent solderability, very fast wetting speed.
- 3) High surface insulation resistance and non-corrosive, cleaning may be eliminated.
- 4) Little scattering of solder, very low fume.
- 5) Clear flux residue offers superior cosmetic.



■ Specifications

Product		JM - 20
Composition	(%)	Sn60, Pb40
Flux content	(%)	1.0 - 3.0
Halide content	(%)	0.0
Silver chromate paper test		No discoloration
Solder spread factor	(%)	90
Solder wetting speed* ¹ (sec.)		< 0.5
Aqueous solution resistivity (Ω .cm)		> 1 × 10 ⁵
Surface insulation resistance* ²	Initial value	> 1 × 10 ¹³
	After humidification (Ω)	> 1 × 10 ¹²
Copper corrosion* ³	Copper plate	Passed
	Copper mirror	Passed
Flux residue stickiness (by chalk powder)		No attachment
Wire diameter	(mm)	0.5, 0.6, 0.8, 1.0, 1.2

1. Solder wetting speedBy Meniscograph with copper plate (30×7×0.2mm) at 230°C
2. SIR40°C×90%×RH×96Hr
3. Aqueous solution resistivityIn accordance with MIL specifications.
4. Copper corrosionIn accordance with JIS.